



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



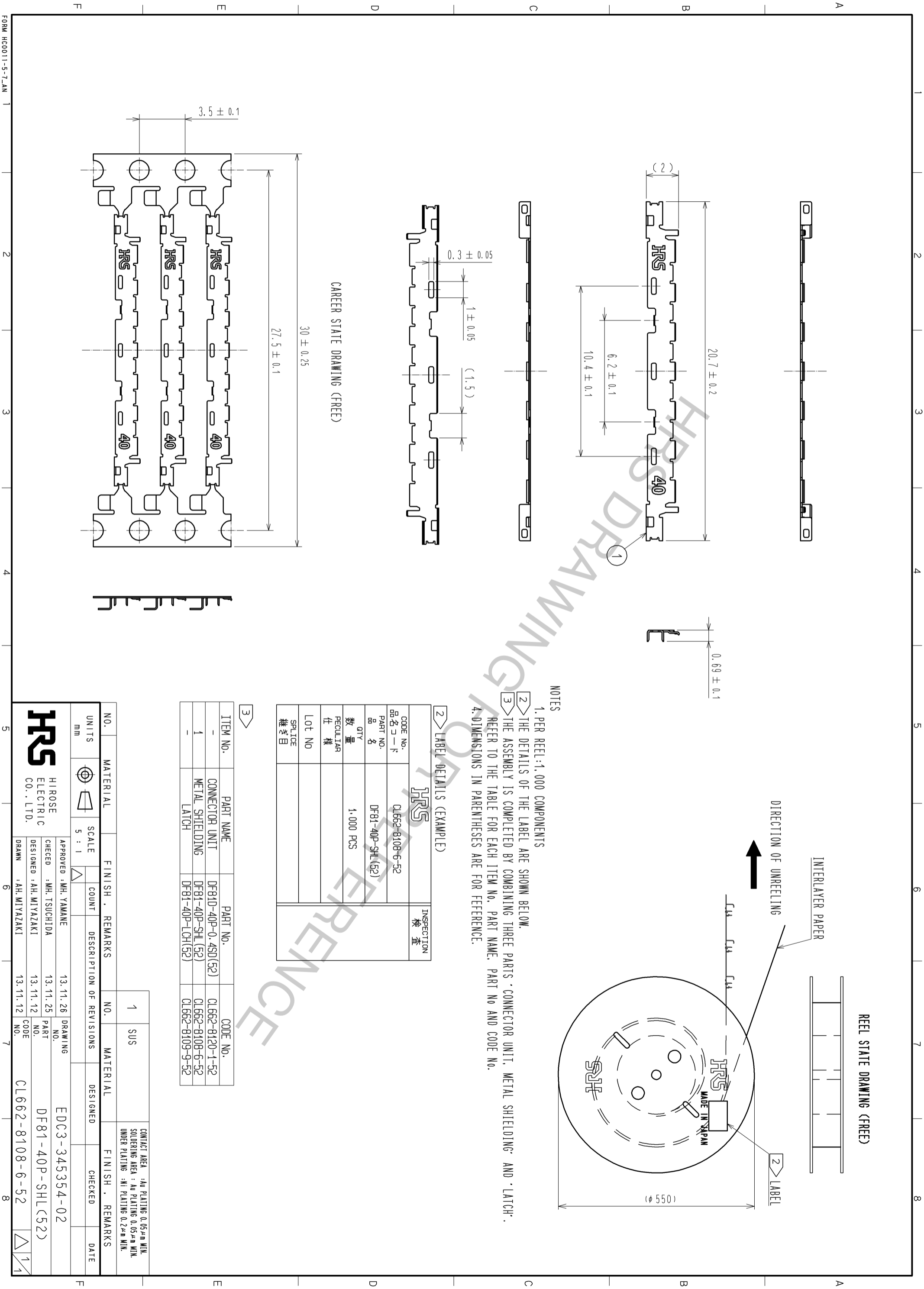
## Contact us

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- NOTES
1. PER REEL: 1,000 COMPONENTS
  2. THE DETAILS OF THE LABEL ARE SHOWN BELOW.
  3. THE ASSEMBLY IS COMPLETED BY COMBINING THREE PARTS: CONNECTOR UNIT, METAL SHIELDING, AND LATCH.
  4. DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

2 LABEL DETAILS (EXAMPLE)

CODE No. 品名コード	CL662-8108-6-52	INSPECTION 検査
PART NO. 部品名	DF81-40P-SHL(52)	
QTY 数量	1,000 PCS	
REGULAR 仕様		
Lot No		
SPLICE 継ぎ目		

3

ITEM NO.	PART NAME	PART NO.	CODE NO.
-	CONNECTOR UNIT	DF81D-40P-0.4SD(52)	CL662-8120-1-52
1	METAL SHIELDING LATCH	DF81-40P-SHL(52)	CL662-8108-6-52
-		DF81-40P-LCH(52)	CL662-8109-9-52

NO.	1	SUS	CONTACT AREA : Au PLATING 0.05μm MIN. SOLDERING AREA : Au PLATING 0.05μm MIN. UNDER PLATING : Ni PLATING 0.2μm MIN.
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NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
1	SUS			1	SUS		CONTACT AREA : Au PLATING 0.05μm MIN. SOLDERING AREA : Au PLATING 0.05μm MIN. UNDER PLATING : Ni PLATING 0.2μm MIN.

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	5 : 1					

APPROVED : MH. YAMANE	13.11.26	DRAWING NO.	EDC3-345354-02
CHECKED : MH. TSUCHIDA	13.11.25	PART NO.	DF81-40P-SHL(52)
DESIGNED : AH. MIYAZAKI	13.11.12	CODE NO.	CL662-8108-6-52
DRAWN : AH. MIYAZAKI	13.11.12		